

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al.

Filed.: September 18, 2003

Art Unit: 2814

Dkt. No.: END920010135US2

Examiner: Lc, Thao X.

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Title: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES

Honorable Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Final Office Action mailed on March 23, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.

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